

AstroPix – A novel HV-CMOS pixel sensor for space-based experiments

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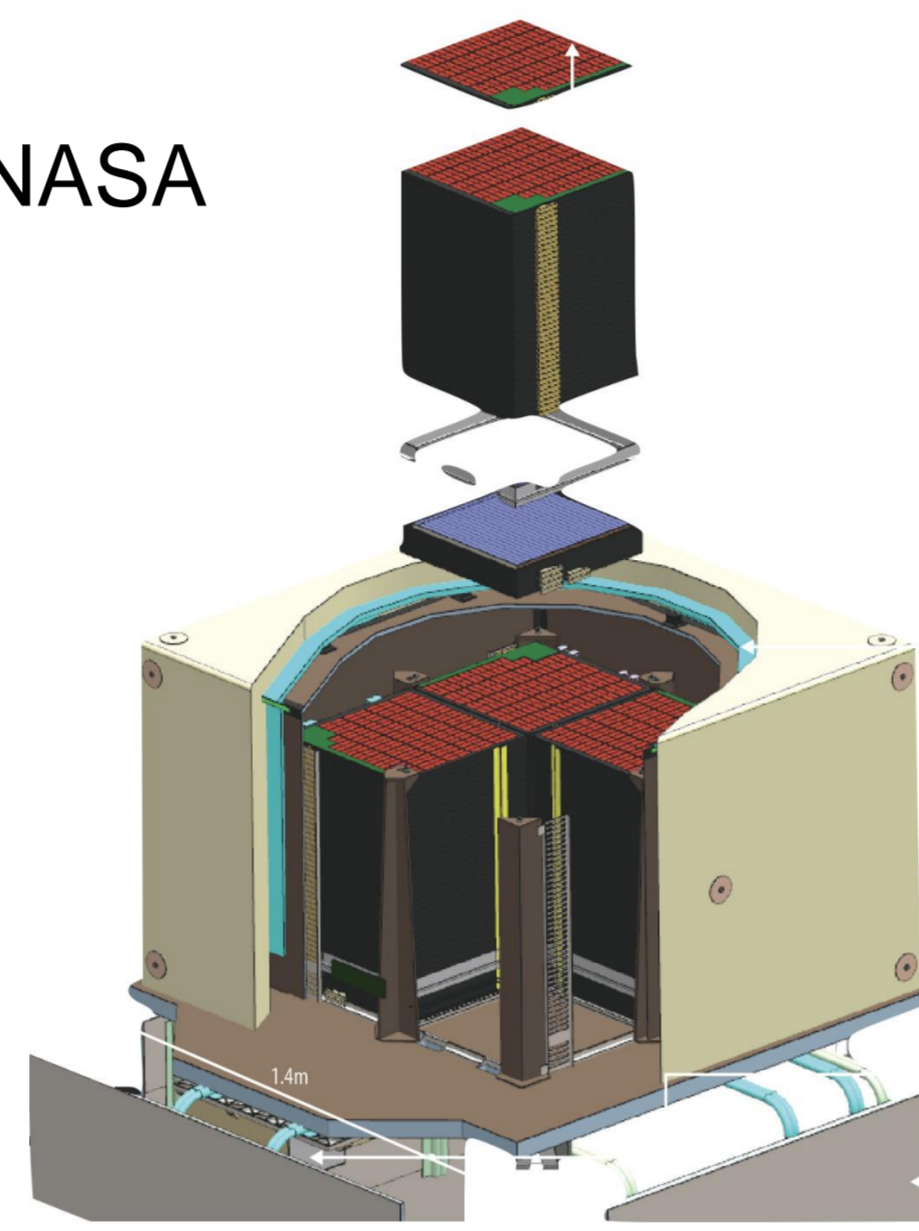
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Motivation: Gamma-ray Astrophysics

- Developed for AMEGO-X mission concept proposed by NASA
- Multi-messenger astronomy
- HV-CMOS based Tracker:
 - 4 Towers with each 40 layers
 - 64000 sensors and 25 m² active area

Requirements:

- Fully depleted 500 μm thick sensors
- Low power 1.5 mW/cm²
- High dynamic range 20 – 700 keV



Caputo, R. et al. "The All-sky Medium Energy Gamma-ray Observatory eXplorer (AMEGO-X) Mission Concept"

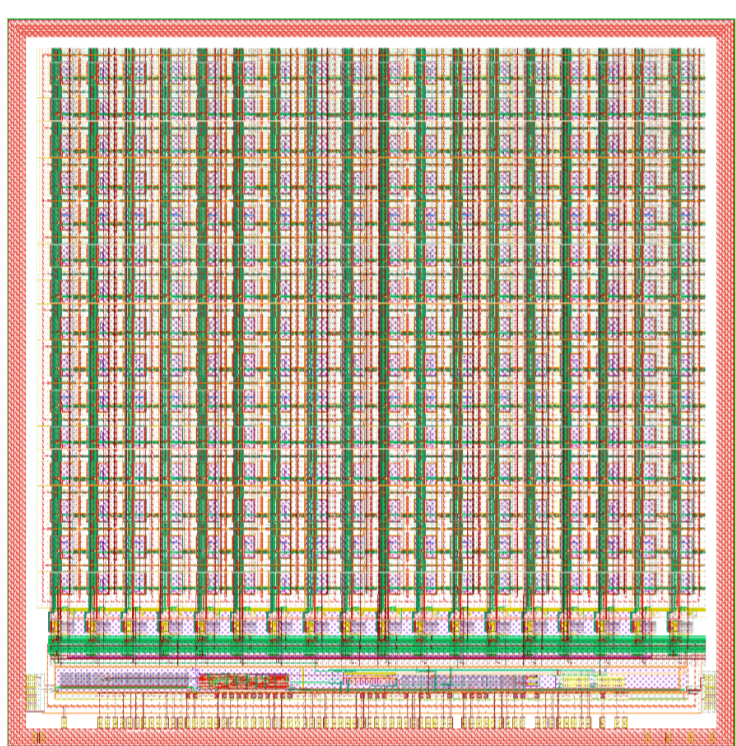
AstroPix3: First full reticle size prototype

- Implemented in TSI 180 nm process
- Submitted in May 2022
- Chip size: 2 cm x 2 cm
- Pixel matrix: 35 columns, 35 rows
- Pixel size: 300 μm x 300 μm
- OR'd row/column-based readout
- ToA: 8 bit counter (2.5 MHz external clock)
- ToT: 12 bit counter (200 MHz external clock)



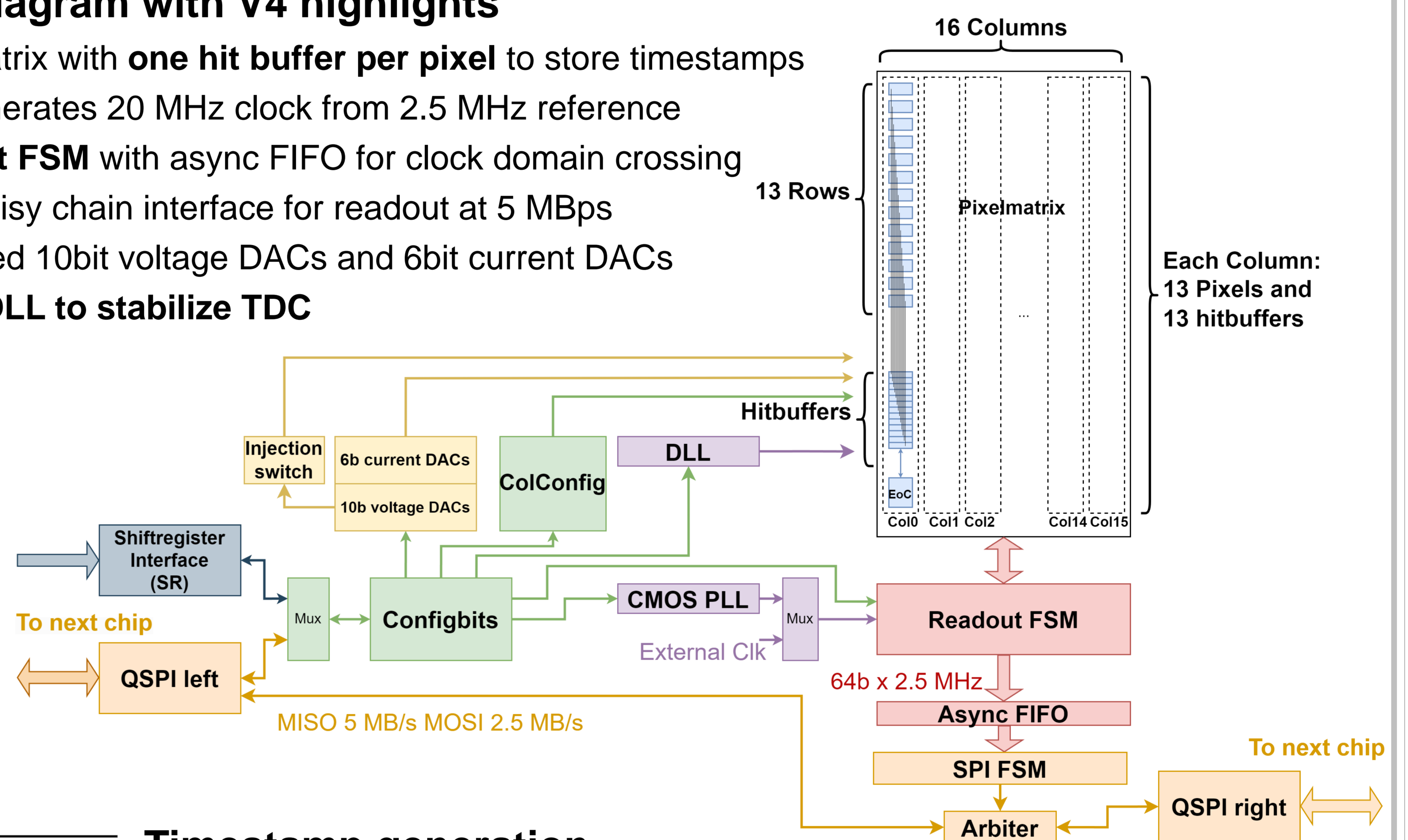
Currently being characterized

AstroPix4



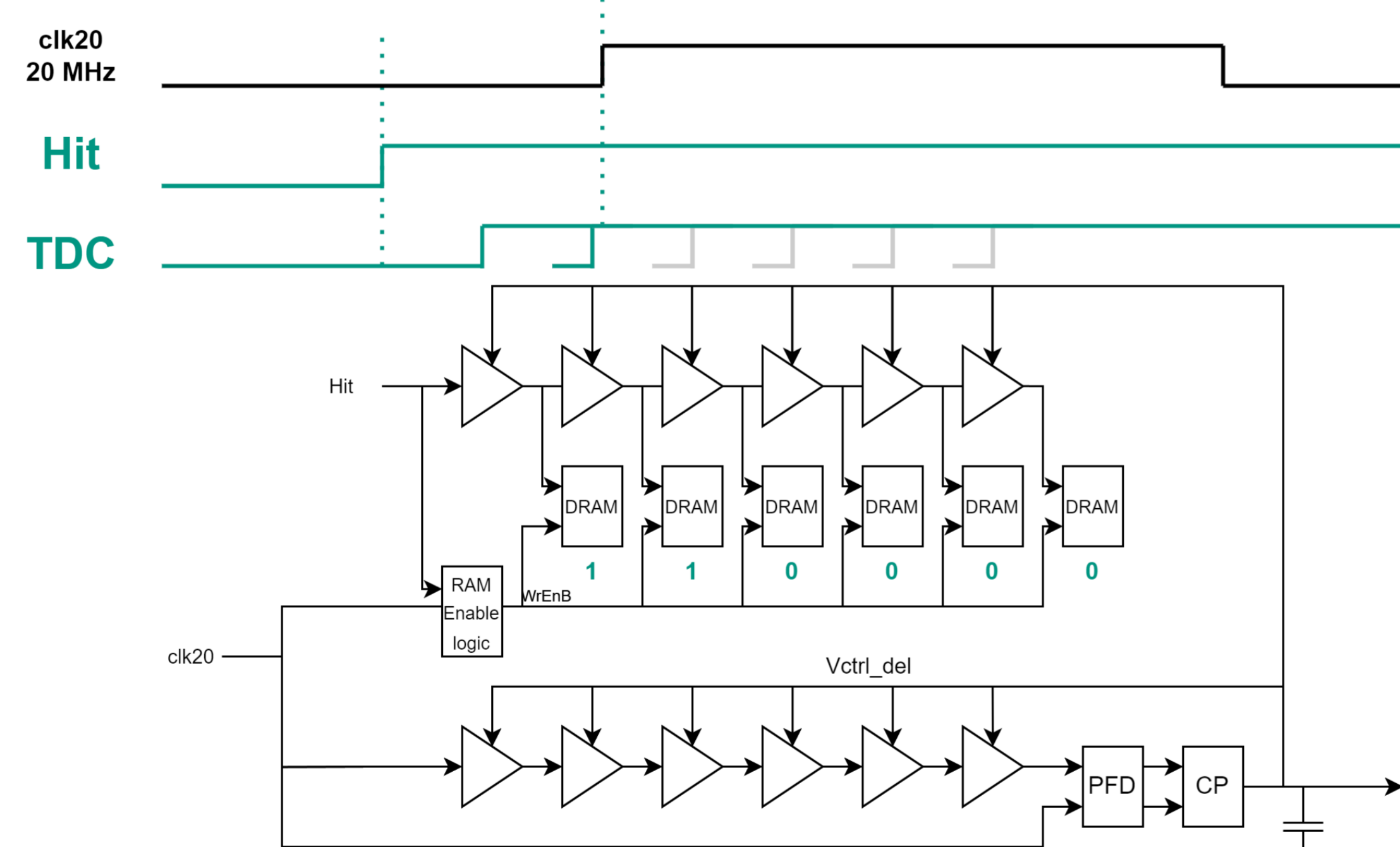
Block diagram with V4 highlights

- Pixel matrix with **one hit buffer per pixel** to store timestamps
- PLL generates 20 MHz clock from 2.5 MHz reference
- Readout FSM** with async FIFO for clock domain crossing
- QSPI daisy chain interface for readout at 5 MBps
- Integrated 10bit voltage DACs and 6bit current DACs
- Global **DLL** to stabilize TDC



Specifications

- 1 x 1 cm² chip in TSI 180nm process
 - Pixel matrix: 16 columns, 13 rows
 - Pixel size: 300 μm x 300 μm
 - Pixel pitch: 500 μm
- ### Improvements over V3
- Per-pixel readout architecture
 - Reduced pixel capacitance by 30%
 - 3 bit TuneDAC per pixel



Timestamp generation

- Coarse timestamps saved in DRAM at leading and trailing edge of a hit
 - 17 bit x 20 MHz generated by global counter
 - 1 bit x 20 MHz negative edge timestamp
- 17 bit Flash-TDC measures time from both edges to next rising clock edge with 3 ns resolution
 - Delay elements based on two current starved inverters
 - Connected to DRAM cells
 - 50 ns total delay controlled by global DLL

Summary

- Submitted new AstroPix4 design in May 2023, currently in production
- Should fulfil AMEGO-x requirements, plan to build balloon prototype (ComPair)
- Improved time-of-arrival resolution from 400 ns and ToT resolution from 5 ns to 3 ns
- Reduced module complexity and power consumption by removal of ext. 200 MHz ToT clock
- Implemented per-pixel readout and tuning capability

Affiliations

- IPE-ADL, Karlsruhe Institute of Technology
- NASA Goddard Space Flight Center
- Hiroshima University
- Argonne National Laboratory
- Institute for Space-Environment Research, Nagoya University